

10/100/1000 BASE DUAL PORT,SURFACE MOUNT MODULES MODEL NO.: IH-033

FEATURE:

RoHS Compliant

RoHS peak solder rating 260°C/ 3~5Sec

Designed to meet IR requirement

SPECIFICATIONS:AT 25°C

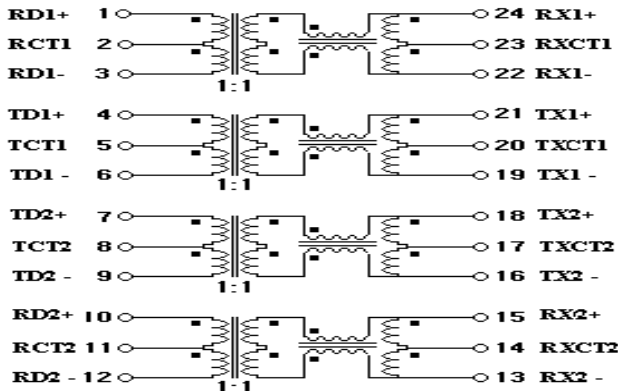
Operating temp : 0°C to +70°C

OCL 350uH MIN. @100KHz 100mV 8mA VDC

Turns Ratio 1CT:1CT (±2 %)

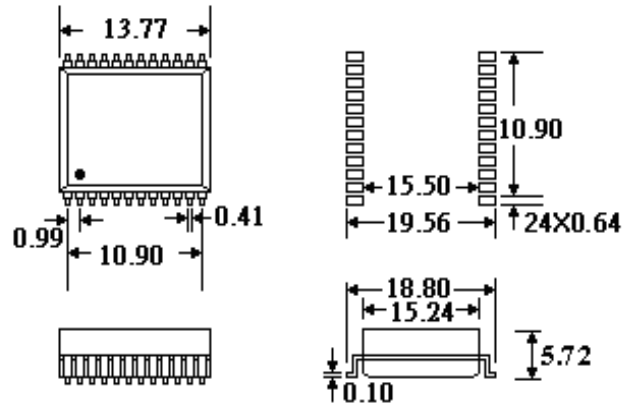
Part Number	InsertionLoss (dB MAX)	Return loss (dB MIN)				Differential to Common Mode Rejection (dB MIN)			Cross talk (dB MIN)			Isolation Voltage (Vrms min)
		MHz		MHz		MHz			MHz			
IH-033	1~100	1~30	40	50	60~80	30	60	100	30	60	100	1500
	-1.1	-16	-14	-13	-12	-43	-37	-33	-45	-40	-33	

SCHEMATICS:

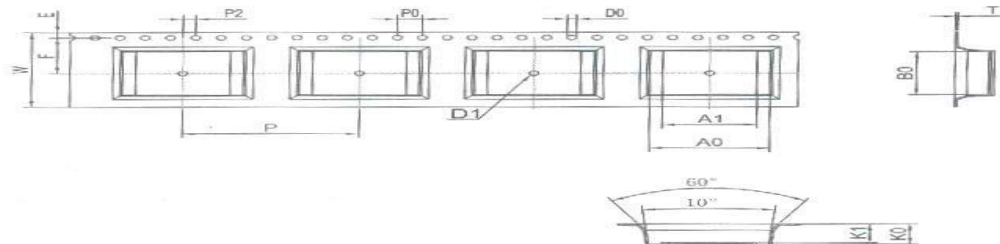


DIMENSION: mm

TOLERANCE: ±0.25



Packing :



并：宋江公差为±0.15MM

ITEM	W ⊕	A. ⊕	A1 ⊕	B. ⊕	B1 ⊕	K. ⊕	K1 ⊕	E ⊕	P ⊕	F ⊕	T ⊕
DIM	24.0 ^{+0.30} _{-0.30}	19.1 ^{+0.25} _{-0.25}	15.0 ^{+0.30} _{-0.30}	13.8 ^{+0.30} _{-0.30}	0.00 ^{+0.30} _{-0.30}	6.10 ^{+0.30} _{-0.30}	5.60 ^{+0.30} _{-0.30}	1.75 ^{+0.30} _{-0.30}	28.0 ^{+0.30} _{-0.30}	11.5 ^{+0.30} _{-0.30}	0.35 ^{+0.05} _{-0.05}

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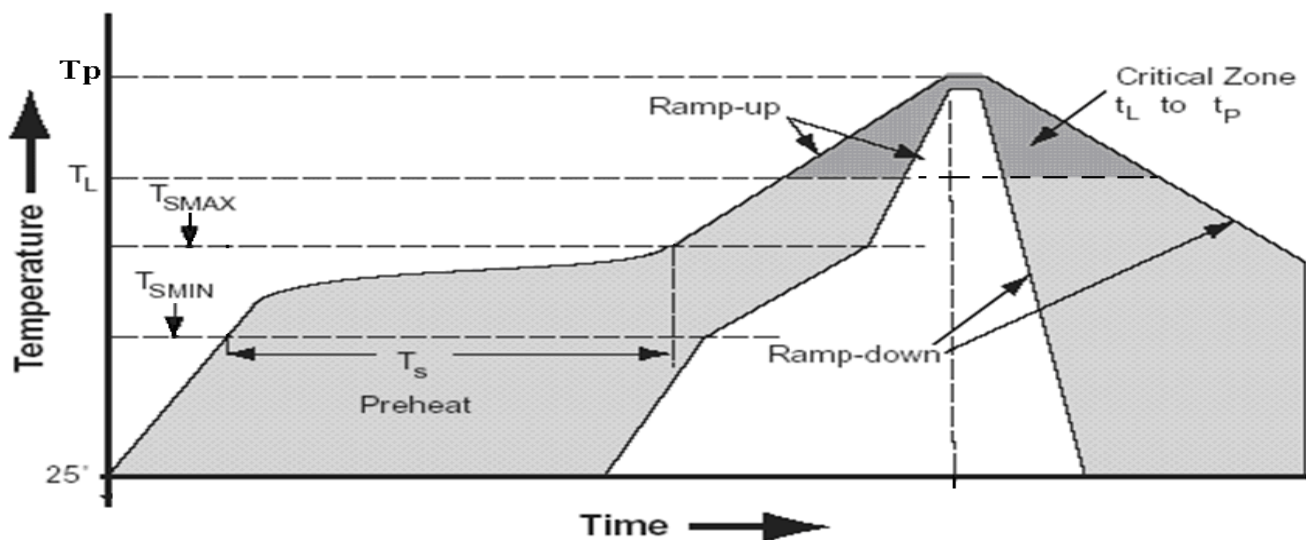
Solder Reflow profile for Lead-Free packages.

Package Peak Reflow Temperatures

Classification Reflow Profiles

Profile Feature	Lead-Free Assembly	
Average ramp-up rate(T_L to T_P)	3°C / Second Max.	
Preheat Temperature Min.(T_s min.) Temperature Max.(T_s max.) Time (min to max) (T_s)	150 °C 200 °C 60-180 sec	
T_s max. to T_L Ramp-up Rate	3°C / Second Max.	
Time maintained above Temperature (T_L) Time (t_L)	217 °C 60-150 sec	
Peak Temp (T_p) Time within 5 °C of actual peak Temp.	260 +0 / -5 °C 3 to 5 Sec	250 +0 / -5 °C 20 to 40 Sec
Ramp-down	6°C / Second Max.	
Time 25 °C to Peak Temperature	8 minutes Max.	

Profile



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PACKING	
1.	Tape & Reel : 400pcs / Reel , 2000pcs / Carton
2.	Dry Pack : 1pcs Product Description:(5g Silica Gel Desiccant) PH: 4-8 Package Materials: Paper(Length 6.5±1cm , Width 5±1cm)
3.	Reel Packed By Vacuum
4.	Seal Per Jedec

